

C L A I M S

WHAT IS CLAIMED IS:

1. A method of packaging a PVA sponge for use in scrubbing semiconductor wafers, said method comprising:
  - (a) placing said sponge in a container;
  - (b) placing in said container a quantity of de-ionized water with around 0.05% to 1% by volume of hydrogen peroxide; and
  - (c) sealing said container.
2. A method as in Claim 1 in which said container is a flexible plastic bag made of a material resistant to deterioration due to contact with hydrogen peroxide, preferably polyethylene.
3. A method as in Claim 1 in which said quantity is at least equal to the amount necessary to saturate said sponge.
4. A method as in Claim 1 in which said amount is around 0.1%.
5. A method of packaging a cleaning article, said method comprising placing said cleaning article in a container, placing in said container a quantity of de-ionized water, said water containing hydrogen peroxide in an amount effective to kill and retard the growth of bacteria in said sponge but less than an amount sufficient to develop significant quantities of metallic ions in said container, and sealing said container.

6. A method as in Claim 5 in which said cleaning article is a PVA sponge brush.

7. A method as in Claim 5 in which said cleaning article is a clean room wiper.

8. A method as in Claim 5 in which said amount is about 0.05 to 1%.

9. A packaged cleaning article for use in clean rooms, said cleaning article having particulate, metal ion and anionic counts at or below the values specified for a clean room, said package comprising a sealed container, said cleaning article being positioned in said container, and a quantity of de-ionized water in said container, said de-ionized water said water containing hydrogen peroxide in an amount effective to kill and retard the growth of bacteria in said sponge but less than an amount sufficient to develop significant quantities of metallic ions in said container.

10. A cleaning article as in Claim 9 in which said amount is around 0.05 to 1% by volume.

11. A cleaning article as in Claim 9 in which said quantity is between an amount sufficient to wet said cleaning article and an amount sufficient to more than saturate said cleaning article.

12. A cleaning article as in Claim 9 in which said cleaning article is a PVA sponge for scrubbing semiconductor wafer surfaces, and said amount is around 0.1 percent.

13. A cleaning article as in Claim 9 in which said cleaning article is a pre-wetted clean room wiper.

14. A cleaning article in which said container is a flexible plastic bag.